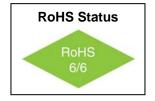
VFH2321-VFH2324 VFH2421-VFH2424 XO Hi-REL, 1.8V 5x7mm SMD, HCMOS



Features

- Leadless chip carrier package is hermetically sealed for superior aging and field performance
- Crystal angle controlled to ±0.5 minute for excellent temperature stability
- 168 hour Class B burn-in and extensive environmental testing for best performance in rugged field environments
- Guarantee start-up with a ramping DC supply
- Start-up time <5ms, typical
- Tristate option available
- Calculated MTBF is 3.8x10⁶ hours at 125°C





Description

These high reliability oscillators provide HCMOS clock waveforms for applications subjected to the most stringent environmental conditions. They are mechanically robust and weigh less than 0.2 grams. This 5x7 mm SMD package has a hermetic seal, thus ensuring the integrity of each oscillator. Each oscillator is burned-in at 125°C for 168 hours, temperature cycled and centrifuged then fully tested in accordance with Table 1. Reliability tests are performed per Table 2. The calculated MTBF is 3.8x10⁶ at 125°C.

Electrical Specifications

Parameter	Symbol	Condition	Min	Тур	Max	Unit	Note
Frequency Range	F		0.85		165	MHz	
Frequency Stability	ΔF/F	Vs. Operating Temperature	±25		±75		See Chart
		Aging 1 st Year After 1 st Year			±3 ±1	ppm	
Operating Temperature Range	Т		-55°		+125°	°C	See Chart
Input Voltage	Vcc		1.7	1.8	1.9	V	
Input Current Icc		850 KHz to 70 MHz, with 15pF load 70.1 to 165.0 MHz with 15pF load		7.0 15.0	10.0 18.0	mA	
Jitter RMS		•			10	ps	
Waveform Symmetry		Measured at 50% V _{DD} 850 KHz to 70 MHz 70.1 to 165.0 MHz		48/52 45/55	45/55 40/60	%	
Rise / Fall Time	Tr/Tf				5	ns	
Output Level		"Zero" Level "One" Level	90% V _{DD}		10% V _{DD}	V	
Input Requirements for Pin 1		"1": On-Pin 1 may float or 90% V_{DD} min. "0": Tristate-Pin 1 requires 10% V_{DD}					



VFH2321-VFH2324 VFH2421-VFH2424 XO Hi-REL, 1.8V 5x7mm SMD, HCMOS



Environmental and Mechanical Conditions

Parameter	Condition			
Storage Temperature	-55°C to +150°C			
Shock	1000 Gs, 0.35 ms, ½ sine wave, 3 shocks in each plane			
Vibration	10-2000 Hz of 0.06" d.a. or 20Gs, whichever is less			
Humidity	Resistant to 85° R.H. at 85°C			
Leak	Per MIL-STD-883, Method 1014, Cond. A1 and Cond.			
Case	Hermetically sealed ceramic LCC			
Pads	15 microinch of gold over nickel			
Resistance to Solvents	Per MIL-STD-202, Method 215			
Marking	Epoxy ink or laser engraved			

FIXED OUTPUT	TRISTATE	Operating	Frequency Stability	
Model	Model	Operating Temperature		
VFH2321	VFH2421	-55°C to +85°C	±25 ppm	
VFH2322	VFH2422	-55°C to +85°C	±50 ppm	
VFH2323	VFH2423	-55°C to +125°C	±75 ppm	
VFH2324	VFH2424	-55°C to +125°C	±50 ppm	

Table 1

Each unit undergoes the following:

1. Stabilization Bake
2. Temperature Cycling
3. Constant Acceleration
4. Burn-in

MIL-STD-883 Method 1008, Cond, B
MIL-STD-883 Method 1010, Cond, B
MIL-STD-883 Method 2001, Cond, A
MIL-STD-883 Method 1015, Cond B

(125°C for 168 hours with bias)
5. Fine Leak MIL-STD-883 Method 1014, Cond. A1
6. Gross Leak MIL-STD-883 Method 1014, Cond C

7. Electrical Test at 25°C and temperature extremes, as follows:

A. Frequency F. Duty Cycle

 $\begin{array}{lll} \text{B. Current} & \text{G. Frequency at max V_{DD}} \\ \text{C. Rise Time} & \text{H. Frequency at min V_{DD}} \\ \text{D. Fall Time} & \text{I. "Zero" logic level} \\ \text{E. Duty Cycle} & \text{J. Tristate} \end{array}$

Test Data on each unit is available for additional cost

Thermal Characteristics

Thermal Resistance

From Junction to Case, RØjc 16 °C/Watt

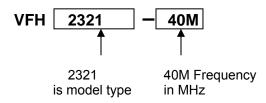
Surface Mount Application

These packages are designed for reflow soldering in accordance with recommended profiles. For hand-soldering, the temperature of the iron should not exceed 400°C for three seconds.

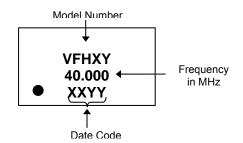




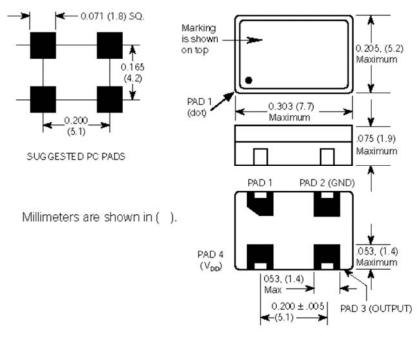
How to Order



Marking Specification



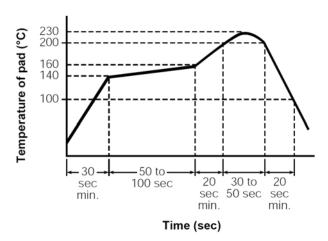
Package



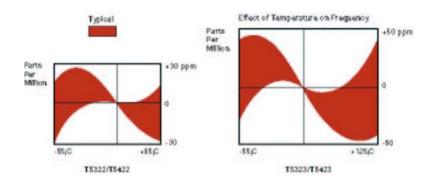
Pad	VFH2321-VFH2324	VFH2421-VFH2424		
1	N/C	Tristate		
2	Ground			
3	Output			
4	Vr	חר		







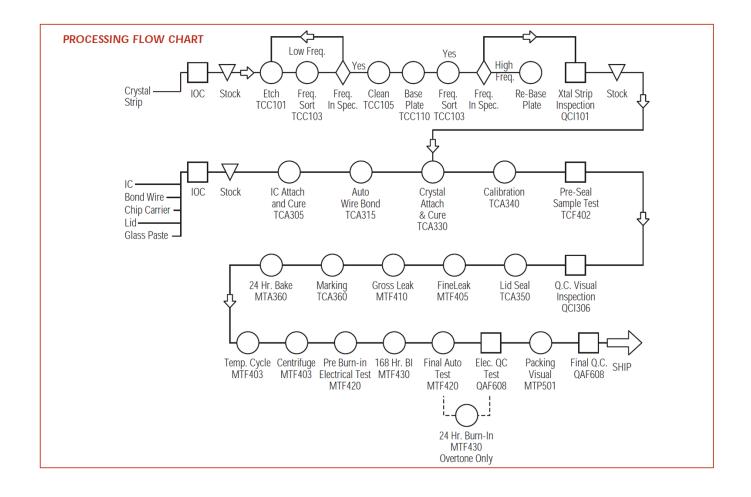
Recommended Reflow Soldering Profile





VFH2321-VFH2324 VFH2421-VFH2424 XO Hi-REL, 1.8V 5x7mm SMD, HCMOS









End point

Detector fluid

TABLE 2 Reliability Test Procedures and Conditions for Quartz Crystal Oscillators

1. Group A

Subgroup 2-4 pcs (One-half of Subgroup 1)

COND. C1

Electrical Characteristics at -55°C, and 125°C (85°C for VFH2321, VFH2421, VFH2322, VFH2422) Frequency @ 1.7, 1.8, and 1.9 volts Symmetry (Duty Cycle) Input current Zero/One levels			<u>Standard</u> MIL-STD-883	Condition Method 1011 COND. B	<u>Descriptio</u> n Thermal Shock Liq. To liq. -55°C to 125°C, 15 cycles	End point Measurement Frequency Output waveform	
Rise/Fall times Physical Dimensions Length/width			MIL-STD-202	MIL-STD-202 Method 105 COND. B		Frequency Output waveform	
Height Seal (Visual) Package finish (Corrosion, discoloration, etc.) Marking placement/legibility 2. Group B- Life Test			MIL-STD-883	Method 1004	Moisture resist. with 1.8V applied 25°C to 65°C, 90 to 100% RH, 10 cycles	Frequency Output waveform	
1000 hrs at or above 125°C, 1.8V VDC, with proper load 3. Group C- All units have passed Group A testing A. Subgroup 1-8 pcs.			MIL-STD-202	Method 210 COND.A	Resistance to Solder Heat Immersion @350°C 3.5 sec	Frequency Output waveform	
Standard Condition			End Point Measurement	C. Subgroups 3-4 pcs. (One half of Subgroup 1)			
MIL-STD-883 Method 2 COND.B	Method 2002 COND.B		Frequency Output waveform	Standard	Condition Storage Temp. No. Oper	Description 24 hrs. @ -55°C 24 hrs. @ 125°C	End point Measurement Frequency Output waveform
MIL-STD-883	Method 2007 COND. A.	Vibration, var. freq. 20 g's, 0.06" disp., 20- 20, 000-20 Hz	Frequency Output waveform	MIL-STD-883	Method 1009 COND. A	Salt Atmosphere 24 hrs. @ 35°C 0.5-3.0% Solution	Frequency Output waveform Visual
MIL-STD-883	Method 2003	Solderability	Visual 95% Coverage	MIL-STD-883	Method 1014 COND. A1	Fine Leak	Qs <5 X10 ⁻⁸
				MIL-STD-883	Method 1014	Gross Leak	Visual in 125°C